TO220F-NL Package Type

1、 目前常规封装为 TO247,封装体积大，散热面积大，一般需要配合散热器紧密贴合。主要应用大功率新能源领域。

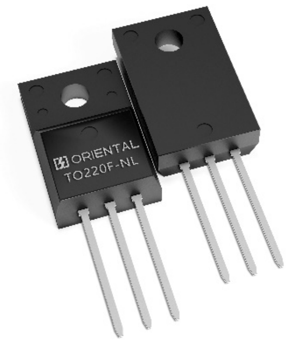
1、Currently, the conventional package type is TO247. It features a large package volume and a large heat dissipation area, and generally needs to be tightly attached to a heat sink for use. It is mainly applied in the field of high-power new energy.

2、TO220F-NL 封装是电子元器件常采用的一种直插式的小型封装形式。产品全塑封，可以实现散热片和外部的电器绝缘。封装体积较小，无需散热器。

2、The TO220F-NL package is a commonly used through-hole small package type for electronic components. Featuring full plastic encapsulation, it enables electrical insulation between the heat sink and the outside. With its relatively small package size, it does not require a heat sink for operation.

3、东微半导体推出 TO220F-NL 封装，具有极大降低开关损耗和杜绝散漏电可能性等优点，可用于高频电源、风力发动机、列车牵引系统等领域。

3、Oriental Semiconductor has launched the TO220F-NL package, which boasts advantages such as drastically reducing switching losses and completely eliminating the risk of leakage current. It is applicable to fields including high-frequency power supplies, wind turbines, and train traction systems.



4、该产品采用全塑封装，在通风条件良好、对绝缘要求较高的应用时，能够杜绝散热片处的电气连接造成漏电的可能性，让电路整体保持良好的绝缘性。产品是具有耐高温特点的单极型器件，可以极大降低开关的损耗，很好的提高整体的效率并减少能量的浪费，同时大大减少产品的体积，这让其在一些高功率密度和空间受限的条件下具有很大的优势。

4、This product adopts full plastic encapsulation. In applications with good ventilation and high insulation requirements, it can completely eliminate the risk of electric leakage caused by electrical connections at the heat sink, thus maintaining excellent insulation performance of the entire circuit. As a unipolar device with high temperature resistance, this product can drastically reduce switching losses, effectively improve overall efficiency and cut down on energy waste. Meanwhile, it significantly reduces product size, which endows it with great advantages in scenarios with high power density and limited space.